IN THE CLAIMS

Please amend the claims as follows, all without prejudice.

1. (Currently Amended) An electrostatic dissipative alignment plate, comprising:

a base adapted to provide an interface between an integrated circuit and a plurality of electrical conductors; and

a frame positioned on the base and adapted to receive the integrated circuit, wherein the base comprises an insulating material and the frame comprises a conducting material, wherein the conducting material has a resistivity of not greater than approximately 10^6 Ohms/sq so that electrostatic charges are dissipated through the frame when the integrated circuit is inserted onto the frame.

2. (Original) The electrostatic dissipative alignment plate of claim 1, wherein the base has a plurality of apertures, wherein each one of the apertures is adapted to align the integrated circuit and to receive one of the plurality of electrical conductors.

3. (Original) The electrostatic dissipative alignment plate of claim 1, wherein the plurality of electrical conductors are coupled to an electrical system.

4. (Original) The electrostatic dissipative alignment plate of claim 1, wherein the integrated circuit comprises a plurality of device leads, wherein each one of the plurality of device leads is in contact with at least one of the plurality of electrical conductors.

5. (Original) The electrostatic dissipative alignment plate of claim 1, further comprising at least one pin adapted to align the frame to the base.

6. (Original) The electrostatic dissipative alignment plate of claim 1, further comprising at least one fastener adapted to attach the frame to the base.

7. (Original) The electrostatic dissipative alignment plate of claim 1, wherein the conducting material has a resitivity of approximately 10^6 Ohms/sq or less and the insulating material has a resitivity of approximately 10^{12} Ohms/sq or greater.

8. (Original) The electrostatic dissipative alignment plate of claim 1, wherein the conducting material is selected from the group consisting of: graphite, carbon filled thermoplastics, Polyetherimide, Polycarbonate, and Acetal Copolymer, and wherein the insulating material is selected from the group consisting of: unfilled thermoplastics, glass-filled thermoplastics, Polyamide-imide, Polyimide, Polyetheretherketone, Polyetherimide, and Polyphenylenesulfide.

9. (Currently Amended) An electrostatic dissipative socket, comprising:

a housing adapted to contain a plurality of electrical conductors;

a base positioned on the housing and adapted to provide an interface between an integrated circuit and the plurality of electrical conductors; and

a frame positioned on the base and adapted to receive the integrated circuit, wherein the base comprises an insulating material and the frame comprises a conducting material, wherein the conducting material has a resistivity of not greater than approximately 10^6 Ohms/sq so that electrostatic charges are dissipated through the frame when the integrated circuit is inserted onto the frame.

10. (Original) The electrostatic dissipative socket of claim 9, wherein the base has a plurality of apertures, wherein each one of the apertures is adapted to align the integrated circuit and to receive one of the plurality of electrical conductors.

11. (Original) The electrostatic dissipative socket of claim 9, wherein the plurality of electrical conductors are coupled to an electrical system.

12. (Original) The electrostatic dissipative socket of claim 9, wherein the integrated circuit comprises a plurality of device leads, wherein each one of the plurality of device leads is in contact with at least one of the plurality of electrical conductors.

13. (Original) The electrostatic dissipative socket of claim 9, further comprising at least one pin adapted to align the frame and the base to the housing.

14. (Original) The electrostatic dissipative socket of claim 9, further comprising at least one fastener adapted to attach the frame and the base to the housing.

15. (Original) The electrostatic dissipative socket of claim 9, wherein the conducting material has a resitivity of approximately 10^6 Ohms/sq or less and the insulating material has a resitivity of approximately 10^{12} Ohms/sq or greater.

16. (Original) The electrostatic dissipative socket of claim 9, wherein the conducting material is selected from the group consisting of: graphite, carbon filled thermoplastics, Polyetherimide, Polycarbonate, and Acetal Copolymer, and wherein the insulating material is selected from the group consisting of: unfilled thermoplastics, glass-filled thermoplastics, Polyamide-imide, Polyimide, Polyetheretherketone, Polyetherimide, and Polyphenylenesulfide.

17. (Currently Amended) An electrostatic dissipative socket assembly, comprising:

a printed circuit board;

a base positioned on the printed circuit board and adapted to provide an interface between an integrated circuit and a plurality of electrical conductors; and

a frame positioned on the base and adapted to receive the integrated circuit, wherein the base comprises an insulating material and the frame comprises a conducting material, wherein the conducting material has a resistivity of not greater than approximately 10^6 Ohms/sq so that electrostatic charges are dissipated through the frame when the integrated circuit is inserted onto the frame.

18. (Original) The electrostatic dissipative socket assembly of claim 17, wherein the base has a plurality of apertures, wherein each one of the apertures is adapted to align the integrated circuit and to receive one of the plurality of electrical conductors.

19. (Original) The electrostatic dissipative socket assembly of claim 17, wherein the conducting material has a resitivity of approximately 10^6 Ohms/sq or less and the insulating material has a resitivity of approximately 10^{12} Ohms/sq or greater.

20. (Original) The electrostatic dissipative socket assembly of claim 17, wherein the conducting material is selected from the group consisting of: graphite, carbon filled thermoplastics, Polyetherimide, Polycarbonate, and Acetal Copolymer, and wherein the insulating material is selected from the group consisting of: unfilled thermoplastics, glass-filled thermoplastics, Polyamide-imide, Polyimide, Polyetheretherketone, Polyetherimide, and Polyphenylenesulfide.